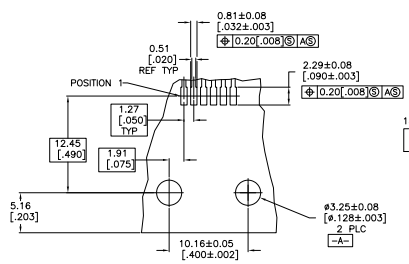
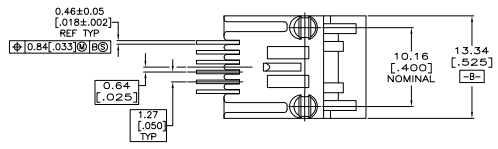
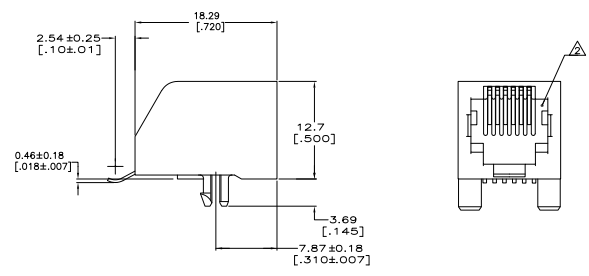
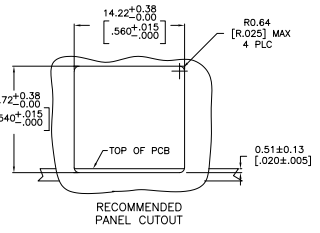


REV	DATE	DESCRIPTION	BY	APP
AA	00			
B1		REVISED PER ECD-11-005033	23MAR11	RK HMR



RECOMMENDED PRINTED CIRCUIT BOARD COMPONENT SIDE



RECOMMENDED PANEL CUTOUT

- MATERIAL: HOUSING- HTN MOLDING COMPOUND, 94V0, COLOR: BLACK.
 TERMINAL- 0.36 [.014] THICK PHOS BRONZE PLATED WITH 1.27µm [.000050] MIN THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81µm [.000150] THICK MATTE TIN IN SOLDER AREA OVER 1.27µm [.000050] MIN THICK NICKEL UNDERPLATE.
 - CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
 - SMP-IN RETENTION FEATURE ACCOMMODATES A 1.57±0.13 [.062±.005] PRINTED CIRCUIT BOARD.
 - DIMENSIONS ARE MAXIMUM UNLESS OTHERWISE SPECIFIED AND ARE PRIOR TO SURFACE MOUNT PROCESSING.
- TERMINALS SHALL BE ASSEMBLED IN CENTER POSITIONS FOR -2.
- 2 PACKAGED 42 ASSEMBLIES PER TUBE.

4	5557314-2
G	5557314-1 (SHOWN)
TERMINALS REQUIRED	PART NO

THIS DRAWING IS A CONTROLLED DOCUMENT.		BY: J. MEYER	ENGR007	DATE: 108-1163	REV: 1
DESIGNER: (signature)	DATE: 114-8040	BY: (signature)	ENGR007	DATE: 108-1163	REV: 1
SEE NOTE 1	SEE NOTE 1	CUSTOMER DRAWING	DATE: 114-8040	REV: 1	REV: 1